



SSC80313GT8

P-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$	I_D
-30V	$\pm 20V$	23m Ω @-10V	-41A
		29m Ω @-4V5	

➤ Description

This device is P-Channel enhancement MOSFET. Uses advanced trench technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

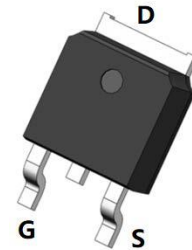
➤ Applications

- Motor Drive Control
- Portable Devices
- DCDC Conversion
- Power Supplies
- Synchronous Rectification

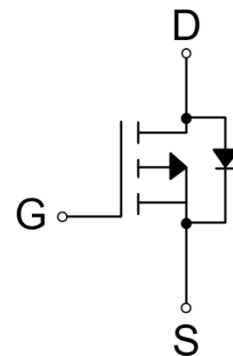
➤ Ordering Information

Device	Package	Shipping
SSC80313GT8	TO-252-2L	2500/Reel

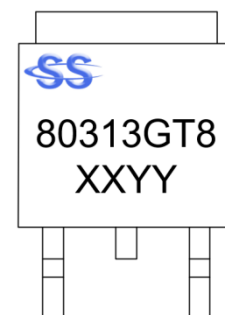
➤ Pin Configuration



TO-252-2L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain-to-Source Voltage		-30	V
V_{GSS}	Gate-to-Source Voltage		± 20	V
I_{D}	Continuous Drain Current ^d	$T_{\text{C}}=25^{\circ}\text{C}$	-41	A
		$T_{\text{C}}=100^{\circ}\text{C}$	-23	
I_{DSM}	Continuous Drain Current ^a	$T_{\text{A}}=25^{\circ}\text{C}$	-10.6	A
		$T_{\text{A}}=70^{\circ}\text{C}$	-7.9	
I_{DM}	Pulsed Drain Current ^b		-164	A
P_{D}	Power Dissipation ^c	$T_{\text{C}}=25^{\circ}\text{C}$	62.5	W
		$T_{\text{C}}=100^{\circ}\text{C}$	25	
P_{DSM}	Power Dissipation ^a	$T_{\text{A}}=25^{\circ}\text{C}$	4.2	W
		$T_{\text{A}}=70^{\circ}\text{C}$	2.7	
E_{AS}	Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse		30	mJ
T_{J}	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance ^a	30	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	2	

Note:

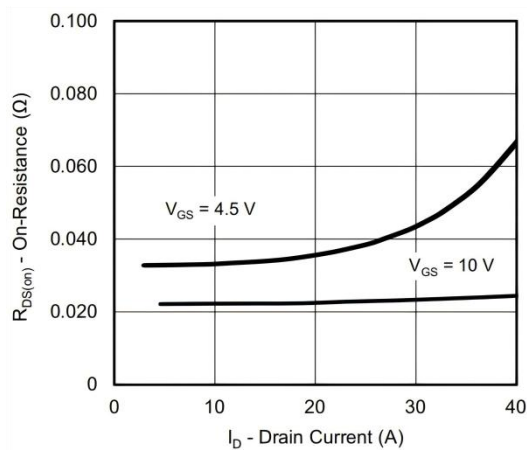
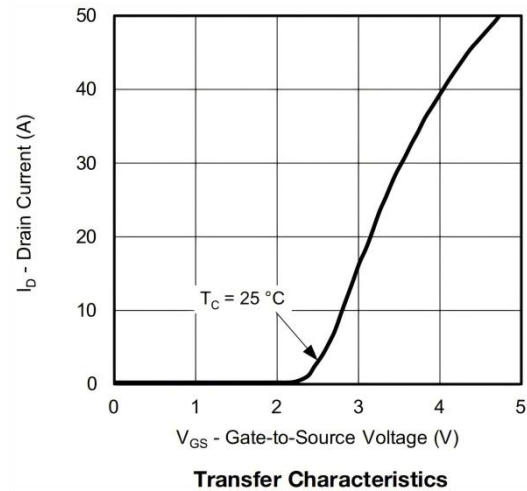
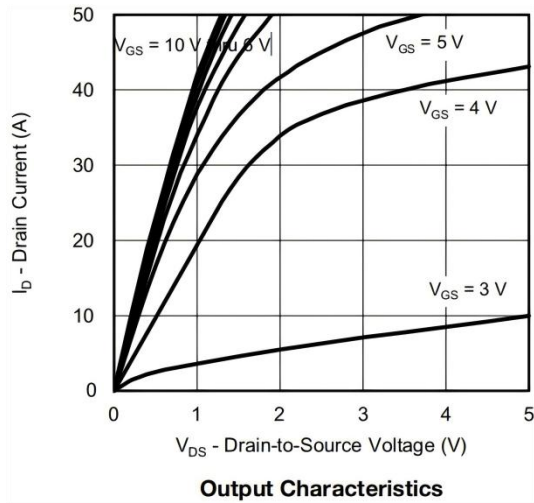
- The value of $R_{\theta\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_{D} is based on $T_{\text{J(MAX)}}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

**➤ Electrical Characteristics (T_A=25°C unless otherwise noted)**

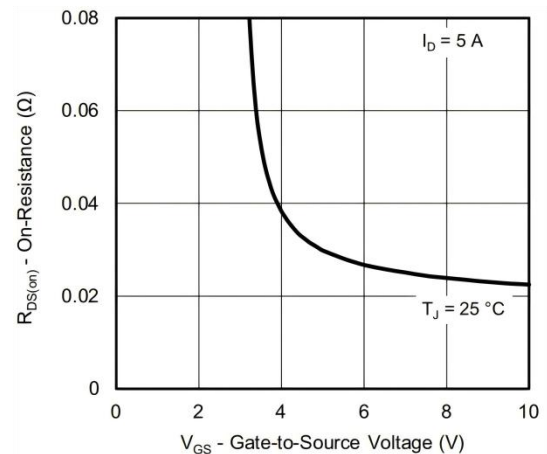
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250uA	-30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250uA	-1	-1.7	-2.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -7A		23	30	mΩ
		V _{GS} = -4.5V, I _D = -4A		29	37	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V			-1	uA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	V _{DS} = -10V, I _D = -5A		11		s
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = -5A		-0.8	-1.3	V
Gate Resistance	R _g	V _{DS} = 0V, f = 1MHz		10.5		Ω
Input Capacitance	C _{ISS}	V _{DS} = -15V, V _{GS} = 0V, f = 1MHz		880		pF
Output Capacitance	C _{OSS}			112		
Reverse Transfer Capacitance	C _{RSS}			92		
Total Gate Charge	Q _G	V _{GS} = -10V, V _{DS} = -15V, I _D = -5A		16		nC
Gate to Source Charge	Q _{GS}			3		
Gate to Drain Charge	Q _{GD}			4.2		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = -10V, V _{DS} = -15V, I _D = -5A, R _G = 3Ω		4		ns
Rise Time	T _r			2		
Turn-off Delay Time	T _{D(OFF)}			39		
Fall Time	T _f			25		



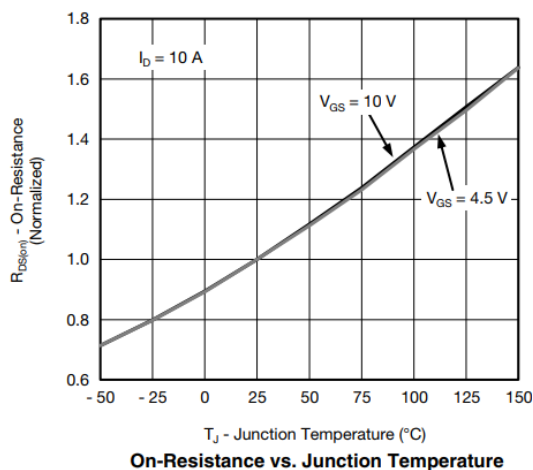
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



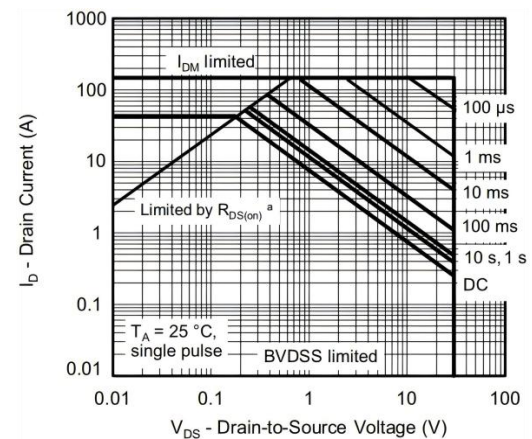
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

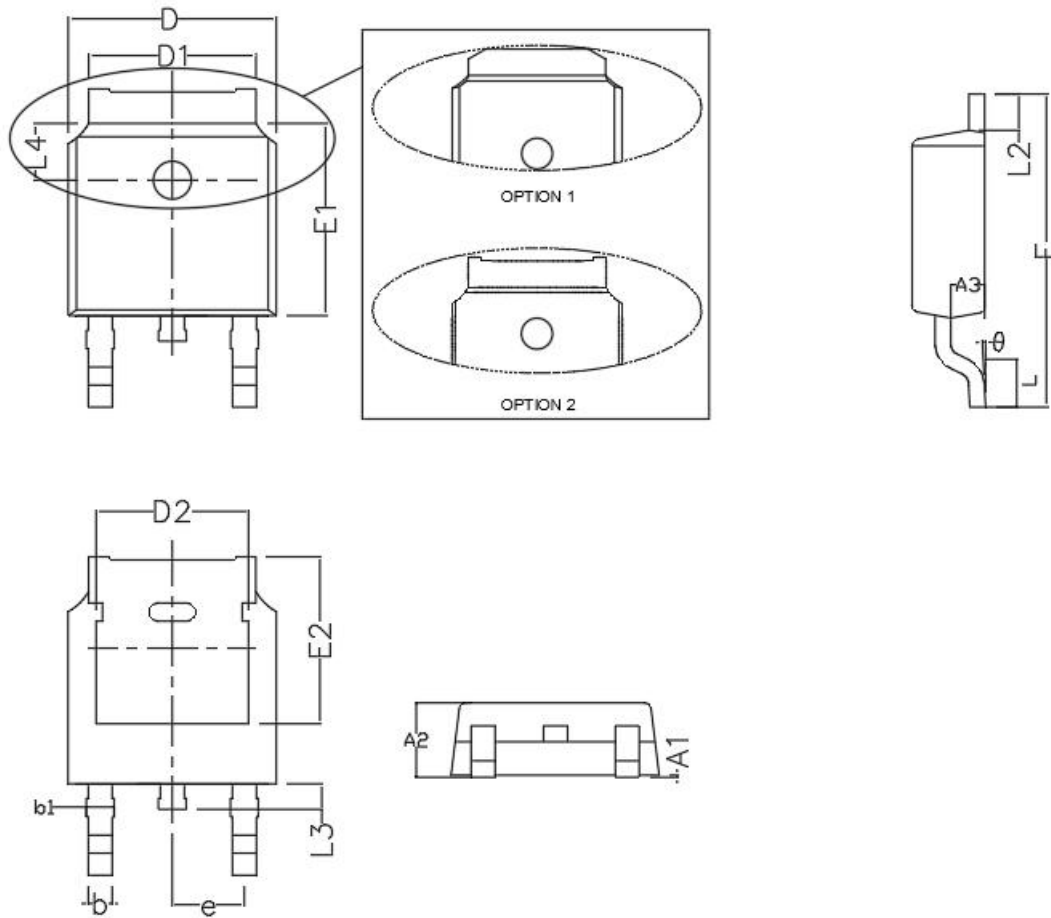


On-Resistance vs. Junction Temperature



Safe Operating Area, Junction-to-Ambient

➤ Package Information



Symbol	MILL IMETER			Symbol	MILL IMETER		
	Min	Nom	Max		Min	Nom	Max
A1	0.000	/	0.200	E1	5.800	6.100	6.400
A2	2.100	2.300	2.500	E2	5.100	5.450	5.600
A3	0.900	1.040	1.170	e	2.286TYP		
b	0.600	0.762	0.910	L	1.270	1.500	2.032
b1	0.680	0.840	1.145	L2	0.900	1.100	1.270
D	6.300	6.600	6.900	L3	0.600	0.800	1.000
D1	4.950	5.330	5.700	L4	1.600	1.800	2.000
D2	4.315	4.830	5.230	θ	0°	/	10°
E	9.395	10.100	10.700				



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